



## Material Content Data Sheet



<b>Sales Product Name</b>		SPD03N60C3		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001145692						
<b>Package</b>		PG-TO252-3-313		<b>Weight*</b>		318.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.326	0.73	0.73	7308	7308
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		463	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	copper	7440-50-8	147.096	46.22	46.28	462258	462860
wire	non noble metal	aluminium	7429-90-5	0.528	0.17	0.17	1659	1659
encapsulation	organic material	carbon black	1333-86-4	1.413	0.44		4442	
	plastics	epoxy resin	-	24.735	7.77		77729	
	inorganic material	silicondioxide	60676-86-0	115.192	36.20	44.41	361997	444168
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11753	11753
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4464	4475
solder	noble metal	silver	7440-22-4	0.059	0.02		186	
	non noble metal	tin	7440-31-5	0.047	0.01		149	
	non noble metal	lead	7439-92-1	2.259	0.71	0.74	7098	7433
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60266	60344
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com